

Atty. Dkt. No. 039153-0472 (G1177)

Amendments to the Specification:

Please amend the specification as follows:

Please replace paragraph number [0001] with the following rewritten paragraph:

[0001] This application is related to U.S. Patent Application No. 09/994,440, Attorney Docket No. 39153/474 (G1179), entitled **METHOD OF INSERTING ALLOY ELEMENTS TO REDUCE COPPER DIFFUSION AND BULK DIFFUSION; U.S. Patent Application No. _____, Attorney Docket No. 39153/519 (G1224), entitled USE OF MULTIPLE ELEMENTS TO FORM A ROBUST, ELECTROMIGRATION RESISTANT COPPER INTERCONNECT; U.S. Patent Application No. 09/994,395, Attorney Docket No. 39153/457 (G1162), entitled **METHOD OF USING TERNARY COPPER ALLOY TO OBTAIN A LOW RESISTANCE AND LARGE GRAIN SIZE INTERCONNECT; U.S. Patent Application No. _____ 09/994,358, Attorney Docket No. 39153/455 (G1160), entitled **METHOD OF IMPLANTATION AFTER COPPER SEED DEPOSITION; and U.S. Patent Application No. _____ 10/123,751, Attorney Docket No. 39153/529 (G1234), entitled **USE OF ULTR-LOW ENERGY ION IMPLANTATION (ULEII) TO FORM ALLOY LAYERS IN COPPER** which are all assigned to the same assignee as this application.******

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